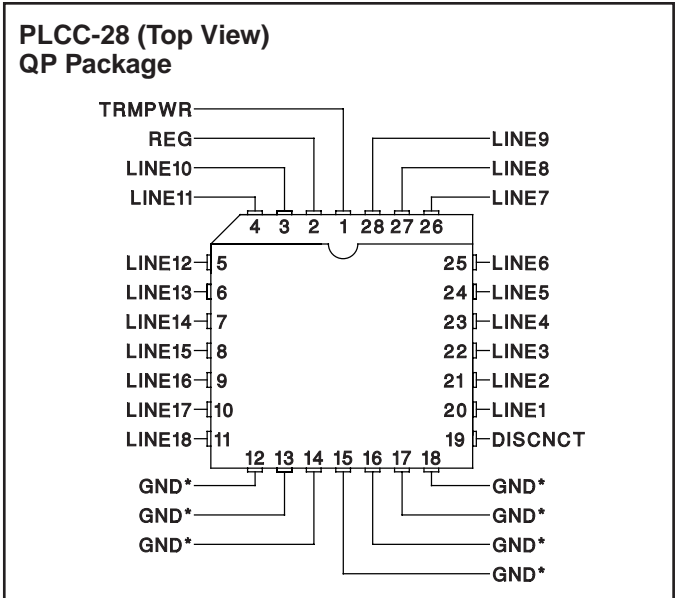


ABSOLUTE MAXIMUM RATINGS

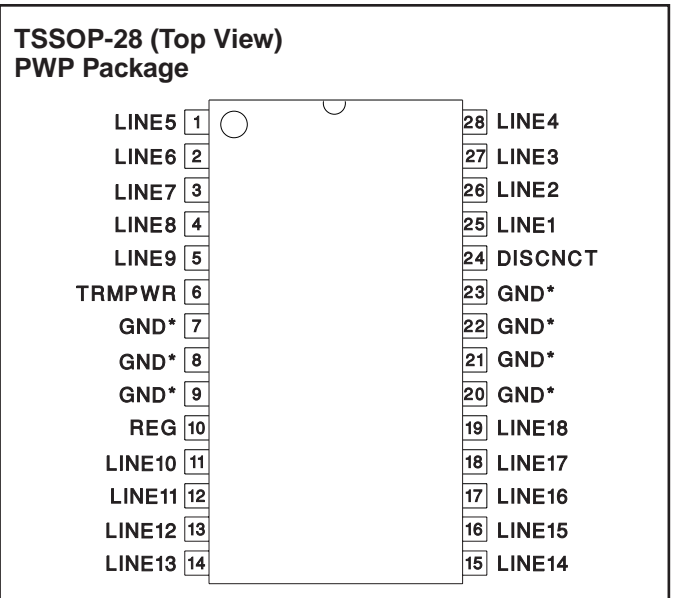
TEMPWR.	+7V
Signal Line Voltage	0V to +7V
Regulator Output Current	1A
Storage Temperature	–65°C to +150°C
Operating Junction Temperature	–55°C to +150°C
Lead Temperature (Soldering, 10 Seconds)	300°C

All currents are positive into, negative out of the specified terminal. Consult Packaging Section of Databook for thermal limitations and considerations of packages.

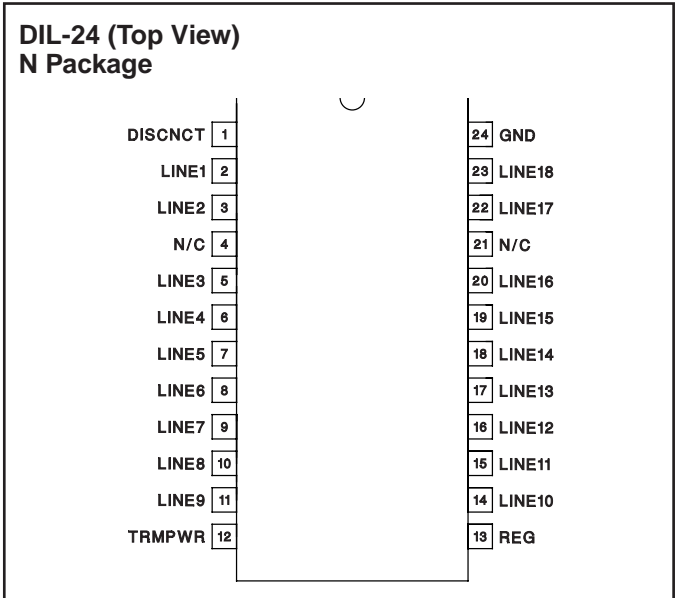
CONNECTION DIAGRAMS



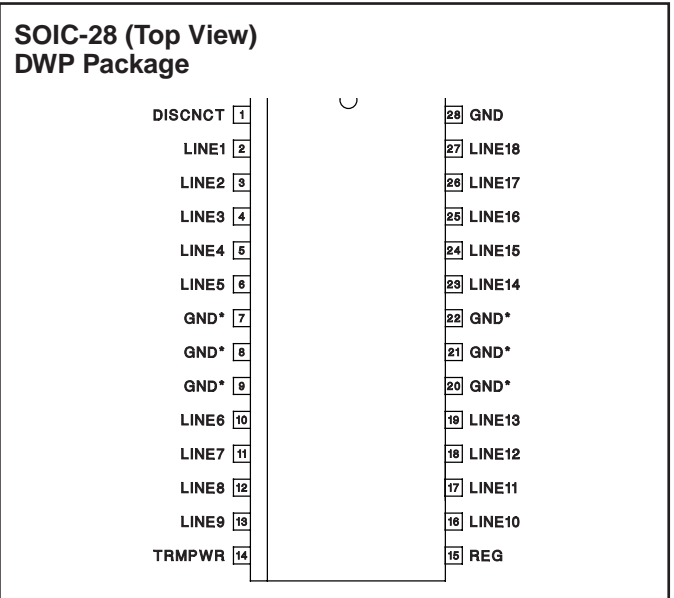
* DWP package pins 12–18 serve as both heatsink and signal ground.



* PWP package pin 23 serves as signal ground; pins 7, 8, 9, 20, 21, and 22 serve as heatsink ground.



Note: Drawings are not to scale.



* DWP package pin 28 serves as signal ground; pins 7, 8, 9, 20, 21, 22 serve as heatsink/ground.

ELECTRICAL CHARACTERISTICS: Unless otherwise stated these specifications apply for $T_A = 0^\circ\text{C}$ to 70°C , $\text{TRMPWR} = 4.75\text{V}$, $\text{DISCNCT} = 0\text{V}$, $T_A = T_J$.

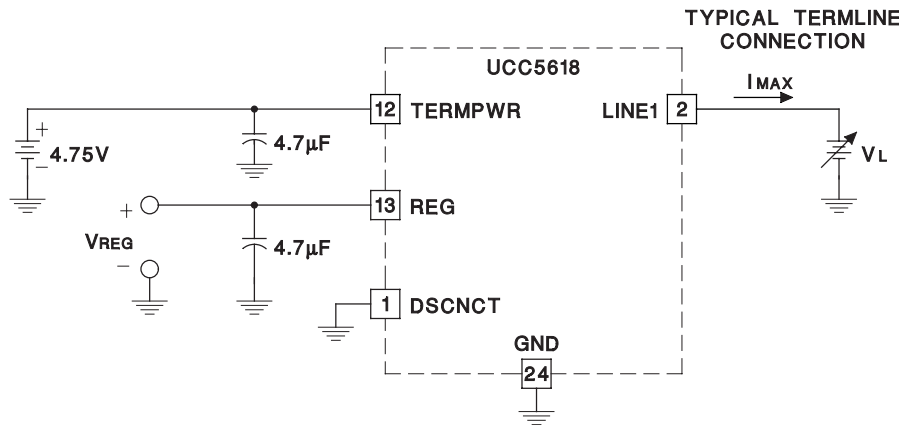
PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Supply Current Section					
TERMPWR Supply Current	All Termination Lines = Open		1	2	mA
	All Termination Lines = 0.2V		420	440	mA
Power Down Mode	DISCNCT = TRMPWR		50	100	μA
Output Section (Termination Lines)					
Termination Impedance	See Figure 1	104.5	110	115.5	Ω
Output High Voltage	$V_{\text{TRMPWR}} = 4\text{V}$ (Note 1)	2.6	2.8	3	V
Max Output Current	$V_{\text{LINE}} = 0.2\text{V}$, $T_J = 25^\circ\text{C}$	-22.1	-23.3	-24	mA
	$V_{\text{LINE}} = 0.2\text{V}$	-20.7	-23.3	-24	mA
	$V_{\text{LINE}} = 0.2\text{V}$, $\text{TERMPWR} = 4\text{V}$, $T_J = 25^\circ\text{C}$ (Note 1)	-21	-23.3	-24	mA
	$V_{\text{LINE}} = 0.2\text{V}$, $\text{TRMPWR} = 4\text{V}$ (Note 1)	-20	-23	-24	mA
	$V_{\text{LINE}} = 0.5\text{V}$			-22.4	mA
Output Leakage	DISCNCT = 2.4V, TRMPWR = 0V to 5.25V, REG = 0.2V, $V_{\text{LINE}} = 5.25\text{V}$		10	400	nA
Output Capacitance	DISCNCT = 2.4V (Note 2)		2	3.5	pF
Regulator Section					
Regulator Output Voltage		2.6	2.8	3	V
Drop Out Voltage	All Termination Lines = 0.2V		0.4	0.8	V
Short Circuit Current	$V_{\text{REG}} = 0\text{V}$	-475	-650	-950	mA
Sinking Current Capability	$V_{\text{REG}} = 3.5\text{V}$	200	400	800	mA
Thermal Shutdown			170		$^\circ\text{C}$
Thermal Shutdown Hysteresis			10		$^\circ\text{C}$
Disconnect Section					
Disconnect Threshold		0.8	1.5	2	V
Input Current	DISCNCT = 0V		-10	-30	μA

Note 1: Measuring each termination line while other 17 are low (0.2V).

Note 2: Guaranteed by design. Not 100% tested in production.

Procedure:

- 1) Measure V_{REG} N.L.
- 2) Set $V_L = 0.2\text{V}$
- 3) Measure I_{MAX} at 0.2V
- 4) Impedance = $\frac{V_{\text{REG}} \text{ N.L.} - 0.2\text{V}}{I_{\text{MAX}}}$



UDG-96102-1

Figure 1. Termline Impedance Measurement Circuit

PIN DESCRIPTIONS

DISCNCT: Taking this pin high or leaving it open causes the 18 channels to become high impedance and the chip to go into low-power mode; a low state allows the channels to provide normal termination.

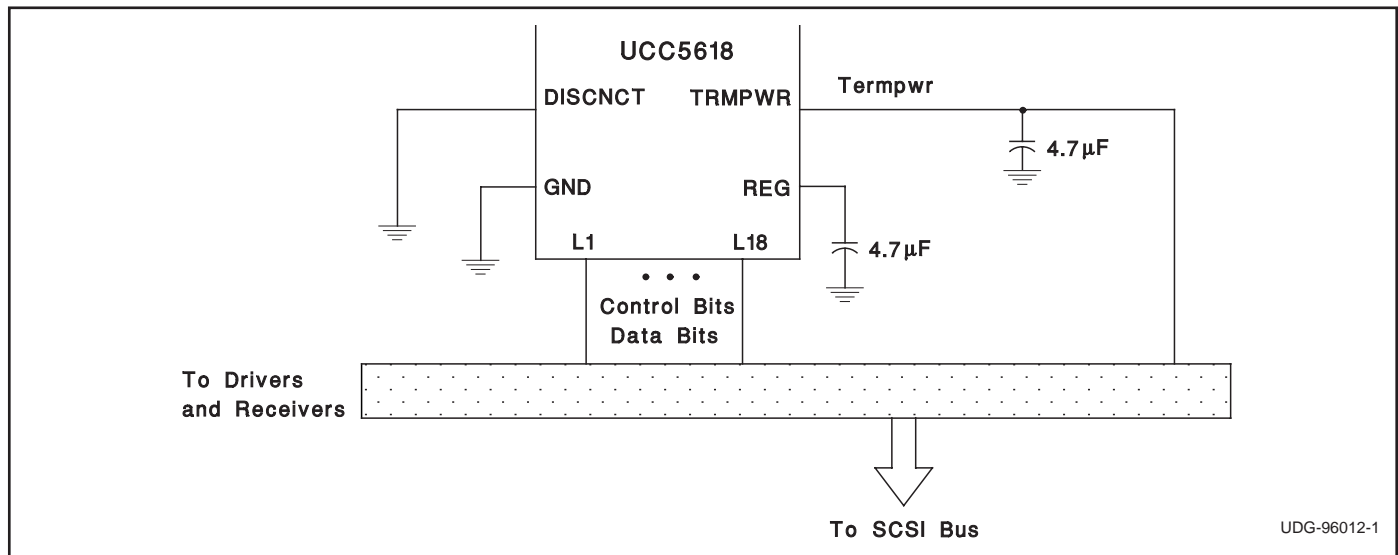
GND: Ground reference for the IC.

LINE1–LINE18: 110Ω termination channels.

REG: Output of the internal 2.8V regulator.

TRMPWR: Power for the IC.

APPLICATION INFORMATION



PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
UCC5618DWP	ACTIVE	SOIC	DW	28	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 70	UCC5618DWP	Samples
UCC5618DWPG4	ACTIVE	SOIC	DW	28	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 70	UCC5618DWP	Samples
UCC5618DWPTR	ACTIVE	SOIC	DW	28	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 70	UCC5618DWP	Samples
UCC5618DWPTRG4	ACTIVE	SOIC	DW	28	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 70	UCC5618DWP	Samples
UCC5618PWP	ACTIVE	TSSOP	PW	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 70	UCC5618PWP	Samples
UCC5618PWPG4	ACTIVE	TSSOP	PW	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 70	UCC5618PWP	Samples
UCC5618PWPTR	ACTIVE	TSSOP	PW	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 70	UCC5618PWP	Samples
UCC5618PWPTRG4	ACTIVE	TSSOP	PW	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 70	UCC5618PWP	Samples
UCC5618QP	ACTIVE	PLCC	FN	28	37	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	0 to 70	UCC5618QP	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

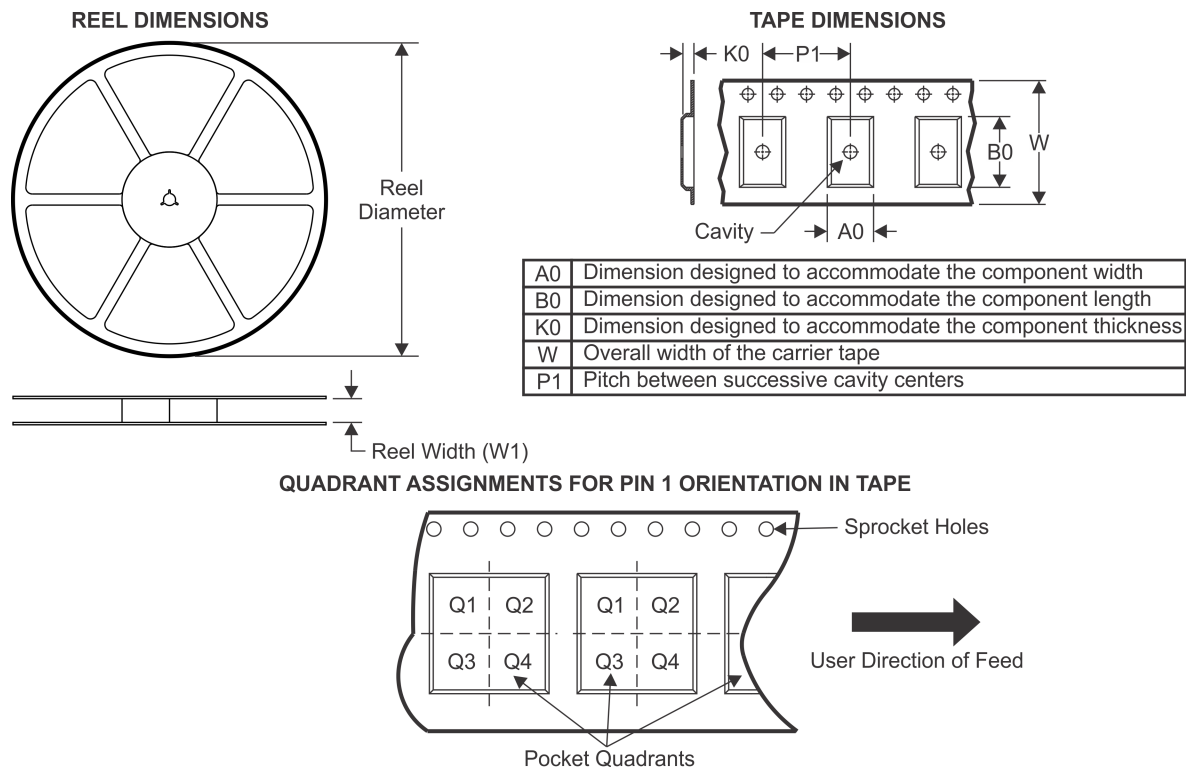
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ Only one of markings shown within the brackets will appear on the physical device.

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TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UCC5618DWPTR	SOIC	DW	28	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UCC5618DWPTR	SOIC	DW	28	1000	367.0	367.0	55.0

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Телефон: 8 (812) 309 58 32 (многоканальный)

Факс: 8 (812) 320-02-42

Электронная почта: org@eplast1.ru

Адрес: 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.